SCBS027A - FEBRUARY 1989 - REVISED JANUARY 1994

 State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ} 	DW OR N PACKAGE (TOP VIEW)
 3-State Outputs Drive Bus Lines or Buffer-Memory Address Registers 	10E 1 20 V _{CC}
P-N-P Inputs Reduce DC Loading	1A1 2 19 2 0E 2Y4 3 18 1Y1
High-Impedance State During Power Up And Power Down	1A2 4 17 2A4
and Power Down	2Y3 5 16 1Y2
 Package Options Include Plastic Small-Outline (DW) Packages and Standard 	1A3 6 15 2A3 2Y2 7 14 1Y3
Plastic 300-mil DIPs (N)	1A4 [8 13 [2A2
	2Y1 🛛 9 12 🗓 1Y4
description	GND [] 10 11 [] 2A1

This cotal buffer and line drive

This octal buffer and line driver is designed specifically to improve both the performance and

density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. Taken together with the SN64BCT240 and SN64BCT241, these devices provide the choice of selected combinations of inverting and noninverting outputs, symmetrical active-low output-enable (\overline{OE}) inputs, and complementary OE and \overline{OE} inputs.

The SN64BCT244 is organized as two 4-bit buffers/line drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the device passes data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

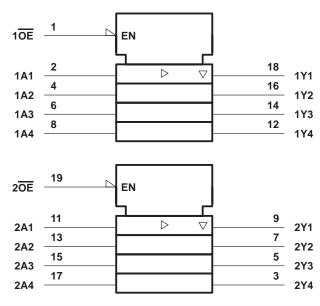
The outputs are in a high-impedance state during power up and power down while the supply voltage is less than approximately 3 V.

The SN64BCT244 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE (each buffer)

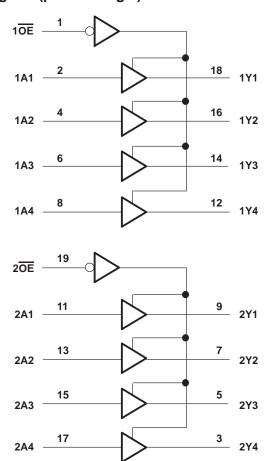
INPU	JTS	OUTPUT
OE	Α	Y
L	Н	Н
L	L	L
Н	Χ	Z

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the disabled or power-off state, VO	
Voltage range applied to any output in the high state, VO	
Current into any output in the low state, IO	128 mA
Operating free-air temperature range	–40°C to 85°C
Storage temperature range	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input negative voltage rating may be exceeded if the input clamp current rating is observed.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
V_{IL}	Low-level input voltage			8.0	V
lik	Input clamp current			-18	mA
loh	High-level output current			-15	mA
loL	Low-level output current			64	mA
TA	Operating free-air temperature	-40		85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST	MIN	TYP [†]	MAX	UNIT		
V _{IK}	$V_{CC} = 4.5 V,$	$I_{I} = -18 \text{ mA}$				-1.2	V
.,	V 45V	$I_{OH} = -3 \text{ mA}$		2.4	3.3		.,
VOH	V _{CC} = 4.5 V	$I_{OH} = -15 \text{ mA}$		2	3.1		V
V _{OL}	$V_{CC} = 4.5 V,$	$I_{OL} = 64 \text{ mA}$			0.42	0.55	V
lį	V _{CC} = 5.5 V,	V _I = 7 V				0.1	mA
lΗ	V _{CC} = 5.5 V,	V _I = 2.7 V				20	μΑ
IĮL	V _{CC} = 5.5 V,	V _I = 0.5 V				-1	mA
1	V _{CC} = 0 to 2.3 V (power up)	V 07V 05V	OE at 0.8 V			± 50	^
loz	$V_{CC} = 1.8 \text{ V to 0 (power down)}$	$V_O = 2.7 \text{ V or } 0.5 \text{ V},$	OE at 0.6 V			± 50	μΑ
lozh	V _{CC} = 5.5 V,	$V_0 = 2.7 \text{ V}$				50	μΑ
lozL	V _{CC} = 5.5 V,	V _O = 0.5 V				-50	μΑ
los†	V _{CC} = 5.5 V,	V _O = 0		-100		-225	mA
ICCH	V _{CC} = 5.5 V,	Output open			23	40	mA
ICCL	$V_{CC} = 5.5 V,$	Output open			53	80	mA
ICCZ	$V_{CC} = 5.5 V,$	Output open			4	10	mA

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

switching characteristics (see Note 2)

•	•	•						
PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _L R1 R2	C = 5 V, = 50 pF = 500 Ω = 500 Ω = 25°C	,	V _{CC} = 4.5 C _L = 50 pl R1 = 500 Q R2 = 500 Q T _A = MIN 1	2, 2,	UNIT
			MIN	TYP	MAX	MIN	MAX	
^t PLH		Υ	1.2	2.5	4.4	0.9	5.3	
t _{PHL}	A	Y	1.7	3.2	5	1.4	6	ns
^t PZH	ŌĒ	V	2	5.7	7.8	2	9	
t _{PZL}	OE .	Y	2	5.9	8.1	2	9.4	ns
^t PHZ	ŌĒ	Y	2	5.4	6.7	2	8	ns
tPLZ	UE UE	1	2	6.1	7.6	2	9.8	115

[§] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN64BCT244DW	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	6BCT244
SN64BCT244DW.A	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	6BCT244

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

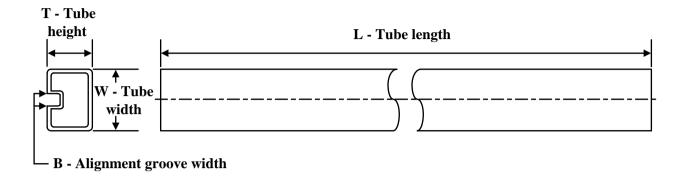
⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

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TUBE

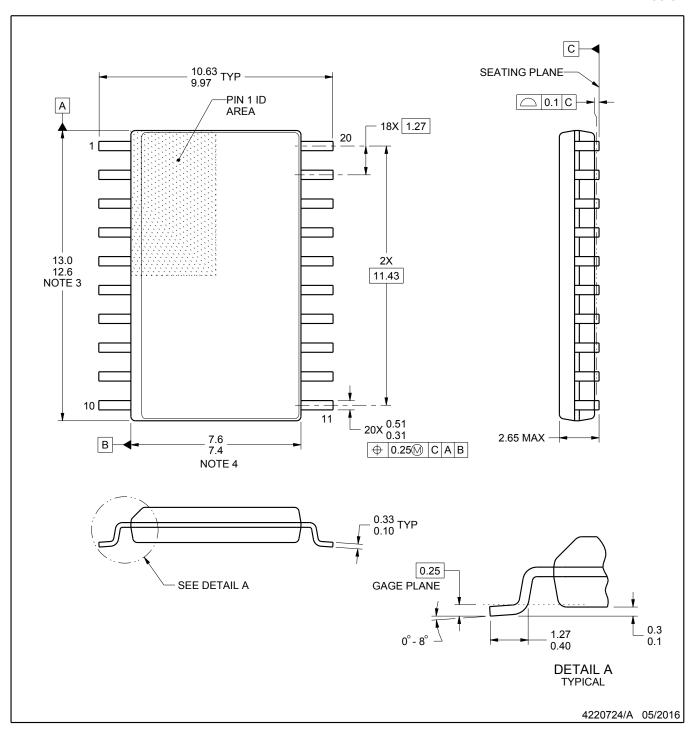


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN64BCT244DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN64BCT244DW.A	DW	SOIC	20	25	507	12.83	5080	6.6



SOIC



NOTES:

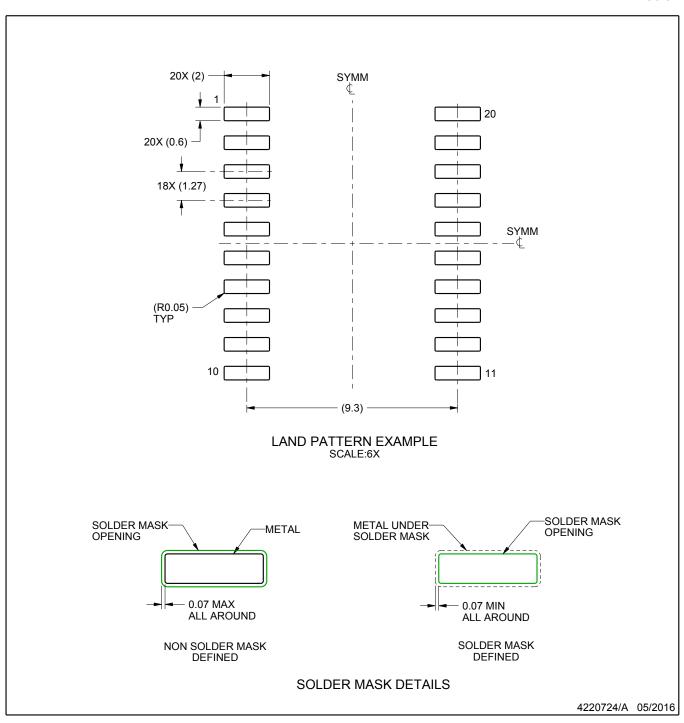
- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



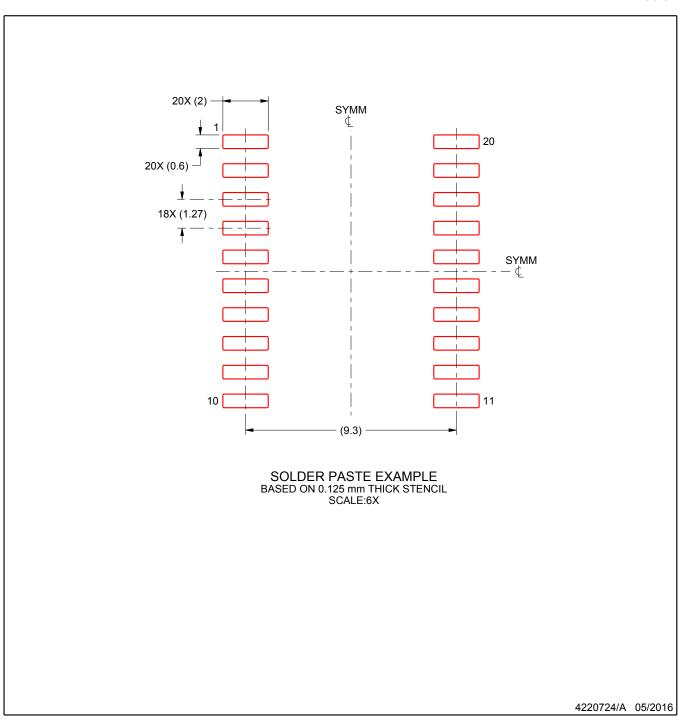
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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Last updated 10/2025